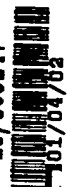


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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

JCS/ 10/19
JC879 U.S. PTO
10/035247



APPL NUM 10035247	FILING DATE 01/04/2002	CLASS 257	SUBCLASS 750	GAU -924 2814	EXAMINER WILSON
**APPLICANTS: Yi Sang Hyun; Kim Young Nam;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: REPUBLIC OF KOREA 2001-8480 02/20/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials				262/009	
TITLE : Semiconductor device having no cracks in one or more layers underlying a metal line layer and method of manufacturing the same					

U.S. DEPT. OF COMMERCE/PAT. & TM. PTC-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
		Applicant Examiner	
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